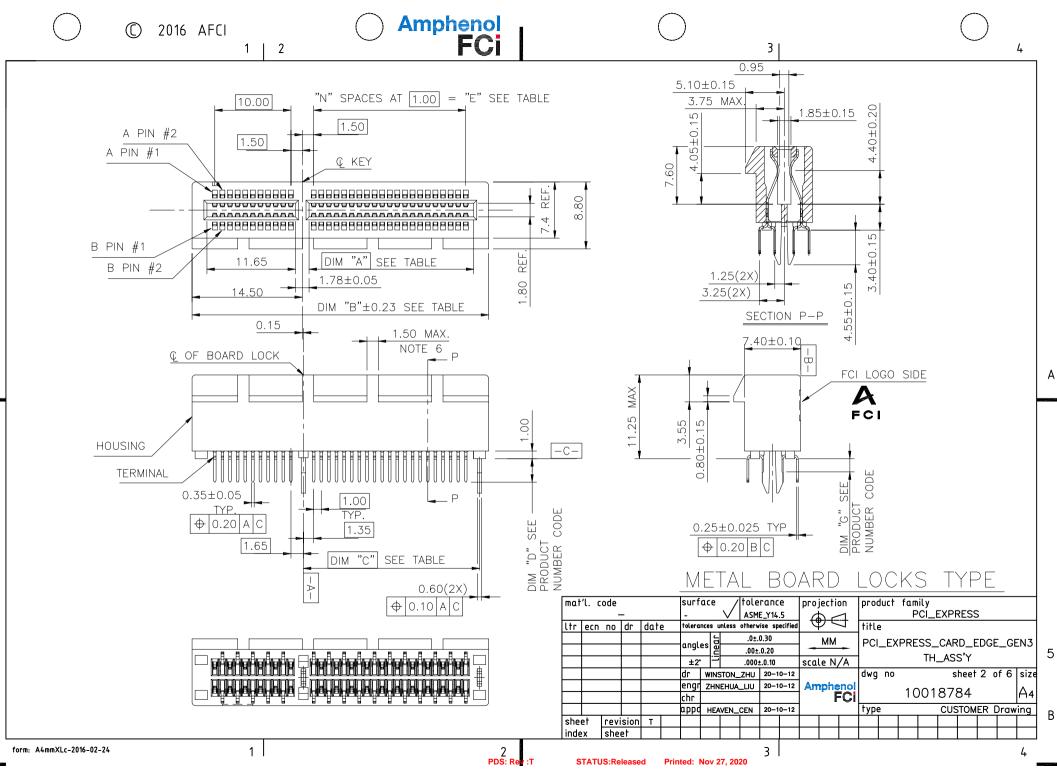


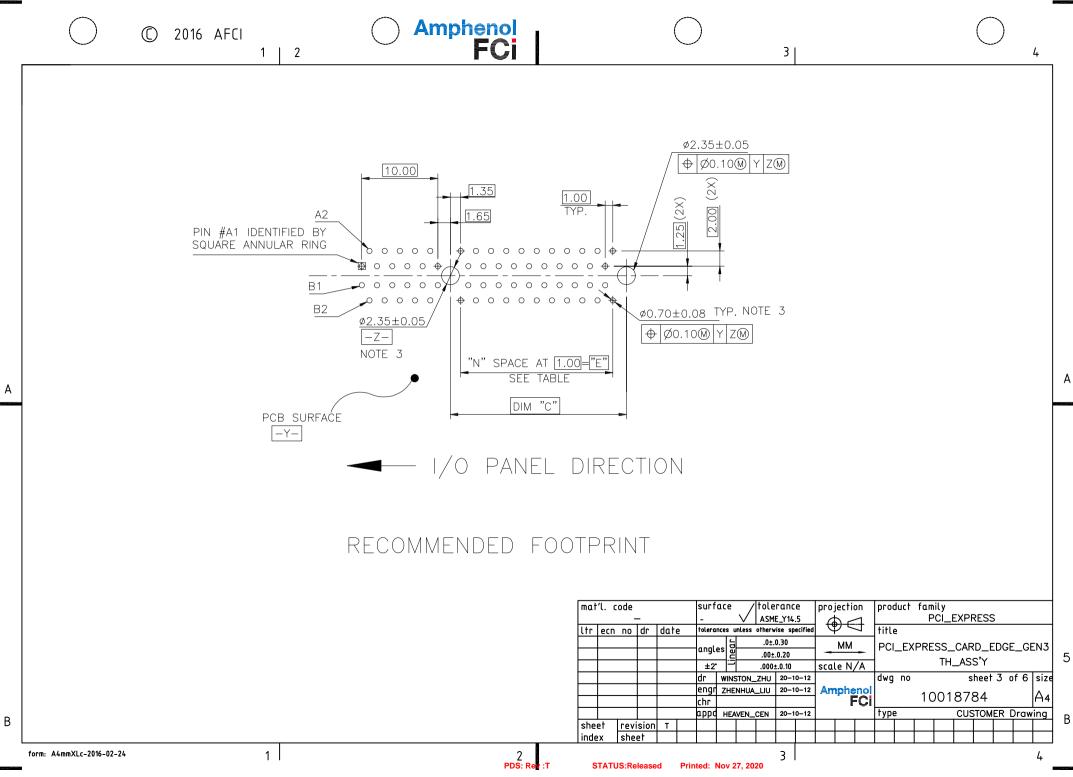
Α

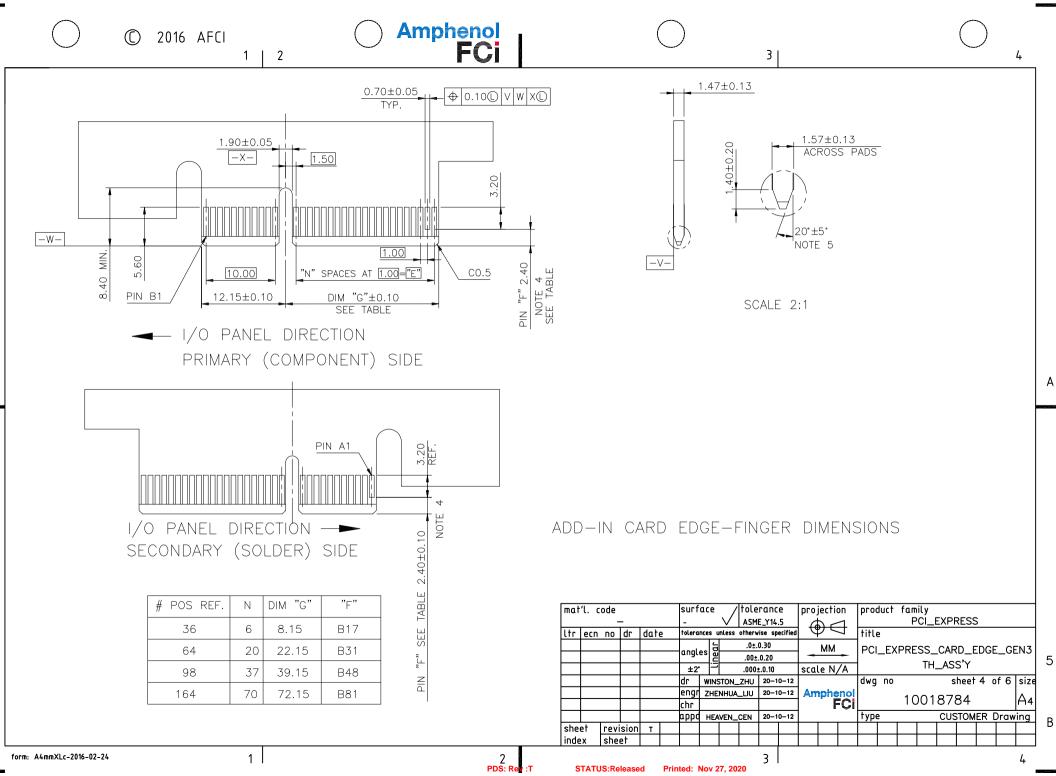
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NOTES:								
1.MATERIAL:								
HOUSING: NYLON, GLASS FILLED UL94V-O RATE, SUITABLE FOR WAVE SOLDERING.								
TERMINAL: COPPER ALLOY PLATING: 50u" NICKEL UNDERPLATE ALL OVER	CONNECTOR	# POS REF.	Ν	DIM "A"	DIM "B"	DIM "C"	"Е"	
CONTACT AREA PLATING – SEE PRODUCT NUMBER CODE SOLDER TAIL: TIN/LEAD (90/10) – SEE PRODUCT	1 PORT	36	6	7.65	25.00	9.15	6.00	
NUMBER CODE 1000" MIN. OVER 500" NICKEL METAL BOARD LOCKS: COPPER ALLOY	4 PORT	64	20	21.65	39.00	23.15	20.00	
FINISH: 100u" TIN/LEAD (90/10) OVER 50u" NICKEL UNDERPLATE SEE PRODUCT NUMBER CODE	8 PORT	98	37	38.65	56.00	40.15	37.00	
2.PRODUCT SPECIFICATION: GS-12-233 ③THE HORIZONTAL AXIS FOR THE HOLE PATTERN IS ESTABLISHED BY			-					
A LINE THROUGH THE CENTER OF THE TWO Ø2.35 HOLES. THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER	16 PORT	164	70	71.65	89.00	73.15	70.00	
OF DATUM Z. (4)NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR								
PINS A1 AND PIN NUMBERS "F".								
⑤CHAMFER EDGES MUST BE FREE OF CUTTING BURRS. ⑥FREQUENCY & LOCATION AT SUPPLIER DISCRETION. RIDGE MAY BE								
CONTINUOUS WITH NO BREAKS. 7.Rohs compatible product specifications								
a - PLATING: - "LF" MEANS THE PRODUCT IS LEAD-FREE, 2um MINIMUM MATTE TIN OVER 1.27um								
MINIMUM NICKEL UNDERPLATE.								
 MANUFACTURING PROCESS COMPATIBILITY THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C±5°C SOLDER BATH TEMPERATURE FOR 								
5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD. – THE HOUSING WILL WITHSTAND EXPOSURE TO 240°C±5°C SOLDER BATH TEMPERATURE FOR								
5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.(For 10018784-X 0 X X X(X X) options)								
PRODUCT NUMBER CODE								
LEAVE BLANK FOR TERMINAL PLATING 3,4,5								
1-BLACK "LF" FOR TERMINAL PLATING OPTION 0,1,2 PACKAGING OPTIONS T-TRAY PACKAGING								
PEGS OPTIONS M-TRAY PACKAGING & MYLAR TAPE FOR PICK-N-PLACE. SEE FIGURE 1								
0-PLASTIC PEGS 1-64								
1-METAL BOARD LOCKS 2-98 3-164								
TERMINAL PLATING OPTIONS TAIL LENGTH OPTIONS								
0-50u" NI UNDERPLATE 30u" AU CONTACT AREA DIM "D" PCB THICKNESS BOARD LOCKS	s dim"g"							
100u" TIN TAIL AREA COMPATIBLE RoHS 1-50u" NI UNDERPLATE 0 2.30 +0.25 1.56±0.10 1.70±0.15	5							
15u" AU CONTACT AREA 100u" TIN TAIL AREA COMPATIBLE ROHS 1 3.10 +0.25 2.36±0.10 2.50±0.15	5							
2-50u" NI UNDERPLATE GOLD FLASH CONTACT AREA		t'l. code	su	rface /to	lerance p	rojection	product family	
100u" TIN TAIL AREA COMPATIBLE RoHS 3-50u" Ni UNDERPLATE			-	A	SME_Y14.5	á- l	PCÍ_EXPRESS	
30u" Au CONTACT AREA 100u" TIN/LEAD TAIL AREA INCOMPLIANT RoHS	ltr	ecn no dr dat	-	erances unless off	erwise specified 0±.0.30		title	
4–50u" NI UNDERPLATE 15u" AU CONTACT ARFA				gles a .	00±.0.20		PCI_EXPRESS_CARD_EDGE_(TH_ASS'Y	GEN3
100u" TIN/LEAD TAIL AREA INCOMPLIANT RoHS 5-50u" NI UNDERPLATE				2*0		cale N/A	dwg no sheet 5 of 6) size
GOLD FLASH CONTACT AREA 100u" TIN/LEAD TAIL AREA INCOMPLIANT RoHS			en	gr ZHENHUA_LI		mphenol FCi	10018784	A4
			chi api	DC HEAVEN_CE			type CUSTOMER Dra	
	she							B
form: A4mmXLc-2016-02-24 1		ex sheet						<u> </u>
form: A4mmXLc-2016-02-24 1 2 3 4 PDS: Ref :T STATUS:Released Printed: Nov 27, 2020 4								

Amphenol FCi

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